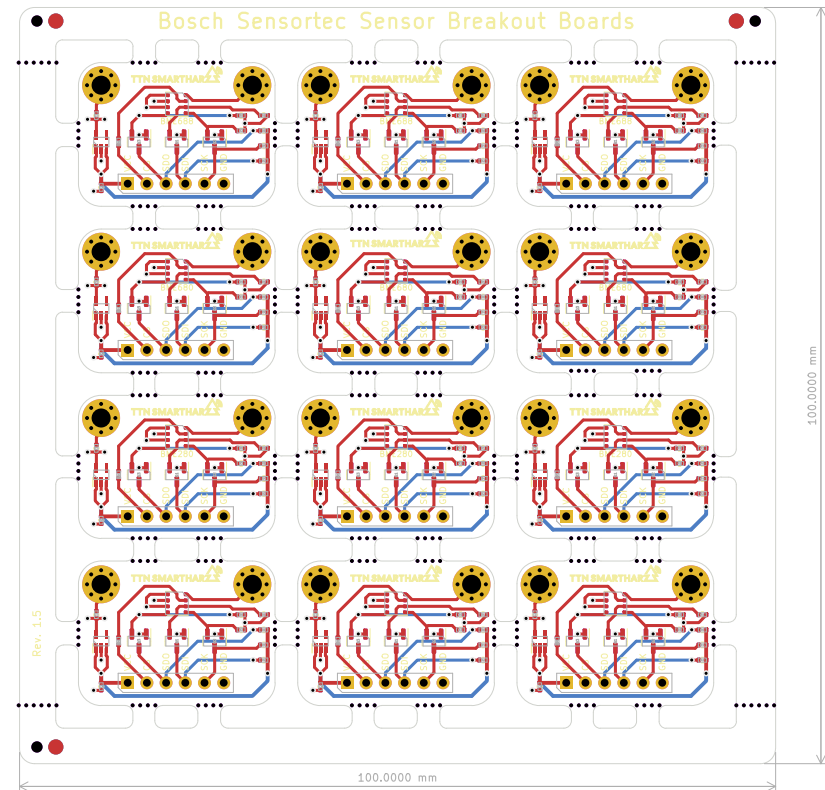


BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.5900 mm
Board overall dimensions: 100.0500 mm x 100.0500 mm
Min track/spacing: 0.2000 mm / 0.0000 mm Min hole diameter: 0.3000 mm
Copper Finish: Immersion gold Impedance Control: No
Castellated pads: No Plated Board Edge: No
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.2 mm		4.5	0.02
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR4	1.065 mm		4.5	0.02
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR4	0.2 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



Benjamin Hüpeden
SmarHarz

Sheet:
File: BME688_Breakout_Board_Panel.kicad_pcb

Title: BST Sensors Breakout Board Panel

Size: A4 Date: 2022-03-15
KiCad E.D.A. kicad (6.0.4)

Rev: 1.5
Id: 1/1

